	Туре	L #	Hits	Search Text	DBs	Time Stamp	Comme nts	Error Definition	E r r
1	BRS	L1	996	(205/81 or 205/101 or 205/787 or 73/61.41).ccls.	USP AT; US- PGP UB; EPO; JPO; DER WEN	2004/04 /23 10:05		•	0
2	BRS	L2	6	1 and (depletion or depleted or shortage) WITH (organic or organics) WITH (compound or compounds or species or additives)	USP AT; US- PGP UB; EPO; JPO; DER WEN	2004/04 /23 10:16			О
3	BRS	L3	0	1 and depletion ADJ of ADJ (organics or organic ADJ compounds)	USP AT; US- PGP UB; EPO; JPO; DER WEN	2004/04 /23 10:15			0

	υ	1	Document ID	Issue Date	Current OR	Current XRef		
1			US 200400558 88 Al	2004032 5	27	Method and apparatus for real time monitoring of electroplating bath performance and early fault detection	205/81	205/82
2			US 200301507 36 Al	2003081 4	13	Apparatus and method for removing contaminants from semiconductor copper electroplating baths	205/99	204/227; 204/275. 1; 204/528; 204/529; 204/634; 205/101; 205/291
3			US 6592737 B1	2003071 5	29	Method and apparatus for determination of additives in metal plating baths	205/81	204/434; 205/789; 205/83
4			US 6280602 B1	2001082	16	Method and apparatus for determination of additives in metal plating baths	205/775	205/776. 5; 205/789; 205/789. 5; 205/81; 702/25
5			US 5935402 A	1999081	7	Process for stabilizing organic additives in electroplating of copper	205/101	205/292; 205/296; 205/297; 205/298
6			US 5538617 A	1996072	14	Ferrocyanide-free halogen tin plating process and bath	205/302	205/101; 205/253

	Retriev al Classif	Inventor	S	С	P	2	3	4	5	Image Doc. Displayed	PT
1		Wikiel, Kazimierz J. et al.	M							US 20040055888	
2		Kovarsky, Nicolay	⊠							US 20030150736	
3		Robertson, Peter M.	Ø							US 6592737	
4		Robertson, Peter M.	×							US 6280602	
5		Fanti, Lisa A.				-				US 5935402	
6		Steinbicker, Richard N. et al.	Ø						0	US 5538617	